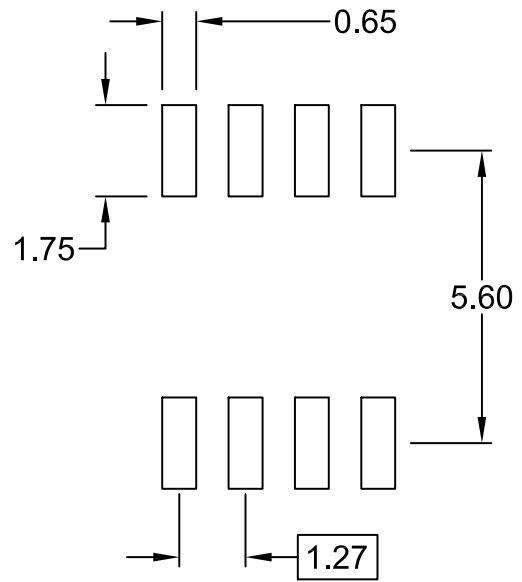
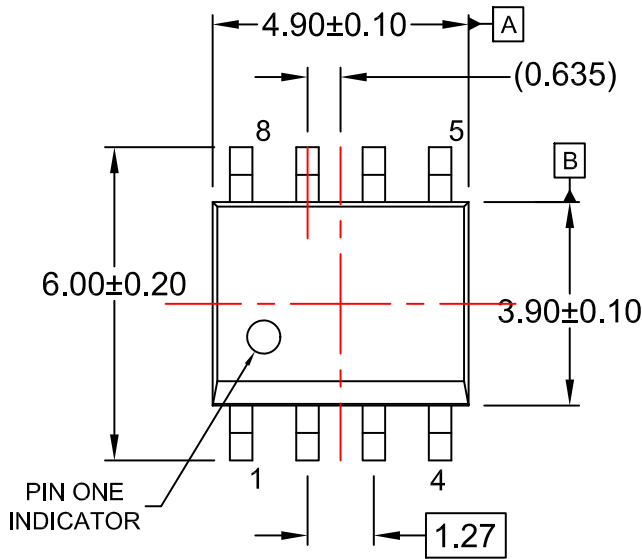


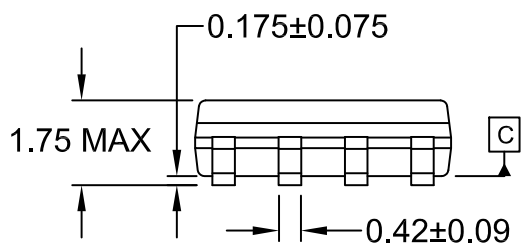
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC8
CASE 751EB
ISSUE A

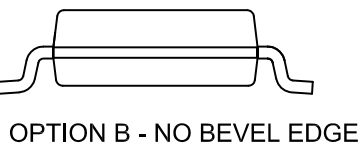
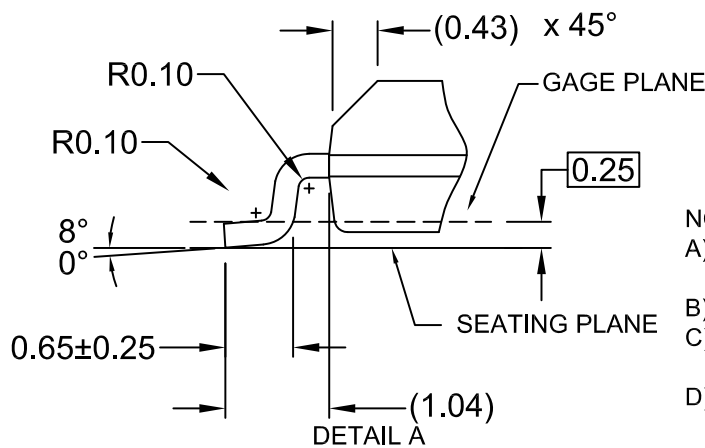
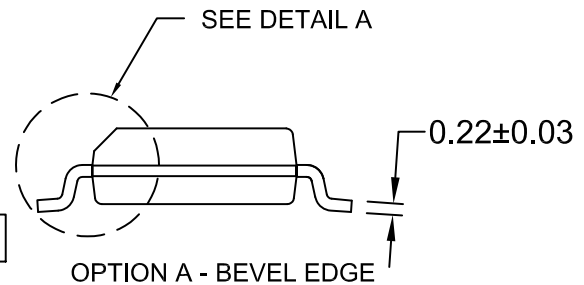
DATE 24 AUG 2017



⊕ 0.25 (M) C B A



⌒ 0.10



- NOTES:
 A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
 D) LANDPATTERN STANDARD: SOIC127P600X175-8M

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